

#### **Description**

The AP120N04P/T uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 10V. This device is suitable for use as a

Battery protection or in other Switching application.

#### **General Features**

V<sub>DS</sub> = 40V I<sub>D</sub> =120 A

 $R_{DS(ON)}$  < 4.0m $\Omega$  @  $V_{GS}$ =10V

#### **Application**

Battery protection

Load switch

Uninterruptible power supply



AP120N04P/T XXX YYYY

### **Package Marking and Ordering Information**

| dokage marking and ordering information |           |                    |          |  |
|---|-----------|--------------------|----------|--|
| Product ID                              | Pack      | Marking            | Qty(PCS) |  |
| AP120N04P                               | TO-220-3L | AP120N04P XXX YYYY | 10 00    |  |
| AP120N04T                               | TO-263-3L | AP120N04T XXX YYYY | 800      |  |

### Absolute Maximum Ratings (T<sub>C</sub>=25°Cunless otherwise noted)

| Symbol                                | Parameter  | Rating     | Units |
|---------------------------------------|--|------------|-------|
| V <sub>D</sub> s                      | Drain-Source Voltage   | 40         | V     |
| Vgs                                   | Gate-Source Voltage  | ±20        | V     |
| I <sub>D</sub> @T <sub>C</sub> =25℃   | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup> | 120        | А     |
| I <sub>D</sub> @T <sub>C</sub> =100°C | Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1,6</sup> | 98         | А     |
| Ірм                                   | Pulsed Drain Current <sup>2</sup>                              | 600        | А     |
| EAS                                   | Single Pulse Avalanche Energy <sup>3</sup>                     | 272        | mJ    |
| las                                   | Avalanche Current  | 33         | Α     |
| P <sub>D</sub> @T <sub>C</sub> =25°C  | Total Power Dissipation <sup>4</sup>                           | 180        | W     |
| Тѕтс                                  | Storage Temperature Range                                      | -55 to 150 | ℃     |
| TJ                                    | Operating Junction Temperature Range                           | -55 to 150 | °C    |
| R <sub>0</sub> JA                     | Thermal Resistance Junction-Ambient <sup>1</sup>               | 50         | °C/W  |
| Rejc                                  | Thermal Resistance Junction-Case <sup>1</sup>                  | 0.7        | °C/W  |





# AP120N04P/T

### **40V N-Channel Enhancement Mode MOSFET**

Electrical Characteristics (TJ=25℃, unless otherwise noted)

| Symbol          | Parameter  | Test Condition   | Min. | Тур. | Max. | Units |
|-----------------|--|--|------|------|------|-------|
| V(BR)DSS        | Drain-Source Breakdown Voltage                           | V <sub>GS</sub> =0V, I <sub>D</sub> =250μA                                 | 40   | 44   | -    | V     |
| IDSS            | Zero Gate Voltage Drain Current                          | V <sub>DS</sub> =40V, V <sub>GS</sub> =0V,                                 | -    | -    | 1.0  | μΑ    |
| IGSS            | Gate to Body Leakage Current                             | V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V                                | -    | -    | ±100 | nA    |
| VGS(th)         | Gate Threshold Voltage                                   | $V_{DS}=V_{GS}, I_{D}=250\mu A$  | 2.0  | 2.8  | 4.0  | V     |
| RDS(on)         | Static Drain-Source on-Resistance note3                  | V <sub>GS</sub> =10V, I <sub>D</sub> =30A                                  | -    | 3.0  | 4.0  | mΩ    |
| Ciss            | Input Capacitance  | V <sub>DS</sub> =20V, V <sub>GS</sub> =0V,<br>f=1.0MHz                     | -    | 4900 | -    | pF    |
| Coss            | Output Capacitance                                       |  | -    | 528  | -    | pF    |
| Crss            | Reverse Transfer Capacitance                             |  | -    | 317  | -    | pF    |
| Qg              | Total Gate Charge  | V <sub>DS</sub> =20V, I <sub>D</sub> =30A,<br>V <sub>GS</sub> =10V         | -    | 80   | -    | nC    |
| Qgs             | Gate-Source Charge                                       |  | -    | 17   | -    | nC    |
| $Q_gd$          | Gate-Drain("Miller") Charge                              |  | -    | 21   | -    | nC    |
| td(on)          | Turn-on Delay Time                                       |  | -    | 21   | -    | ns    |
| t <sub>r</sub>  | Turn-on Rise Time  | $V_{DD}$ =20V, $I_{D}$ =30A, $R_{L}$ =1 $\Omega$ , $R_{GEN}$ =3 $\Omega$ , | -    | 32   | -    | ns    |
| td(off)         | Turn-off Delay Time                                      | V <sub>GS</sub> =10V   | 1    | 71   | -    | ns    |
| t <sub>f</sub>  | Turn-off Fall Time                                       |  | -    | 40   | -    | ns    |
| IS              | Maximum Continuous Drain to Source Diode Forward Current |  | -    | -    | 150  | Α     |
| ISM             | Maximum Pulsed Drain to Source Diode Forward Current     |  | -    | -    | 600  | Α     |
| VSD             | Drain to Source Diode Forward Voltage                    | V <sub>GS</sub> =0V, I <sub>S</sub> =30A                                   | -    | -    | 1.2  | V     |
| t <sub>rr</sub> | Body Diode Reverse Recovery Time                         | T <sub>J</sub> =25℃,<br>I <sub>F</sub> =20A,dI/dt=100A/μs                  | ı    | 27   | ı    | ns    |
| Qrr             | Body Diode Reverse Recovery Charge                       |  | -    | 46   | -    | nC    |

#### Note:

- 1、Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
- 2. The EAS data shows Max. rating . The test condition is T<sub>J</sub>=25  $^{\circ}$ C,V<sub>DD</sub>=20V,V<sub>G</sub>=10V,L=0.5mH,Rg=25 $\Omega$ ,I<sub>AS</sub>=33A
- $3\sqrt{1}$  The data tested by pulsed , pulse width  $\leq 300$ us , duty cycle  $\leq 2\%$
- 4. The power dissipation is limited by 150 °C junction temperature
- $5\sqrt{100}$  The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.
- 6. Package limitation current is 180A



### **Typical Characteristics**

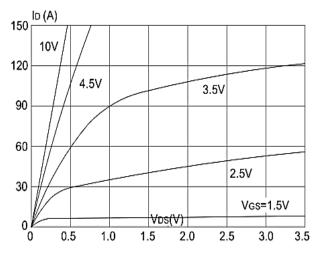
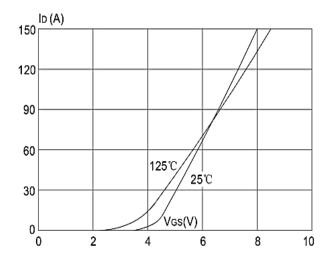


Figure1: Output Characteristics



**Figure 2: Typical Transfer Characteristics** 

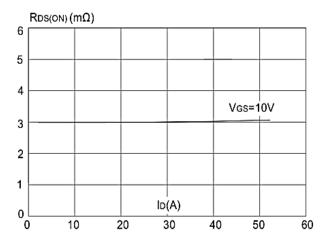
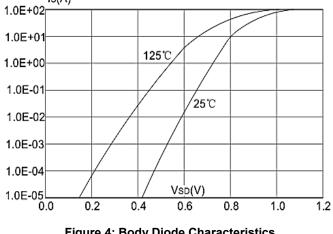


Figure 3:On-resistance vs. Drain Current



**Figure 4: Body Diode Characteristics** 

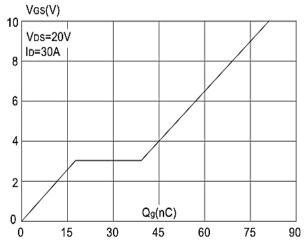


Figure 5: Gate Charge Characteristics

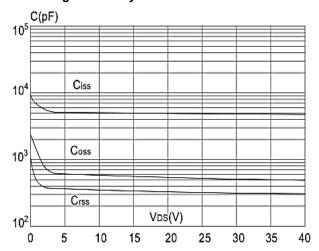


Figure 6: Capacitance Characteristics



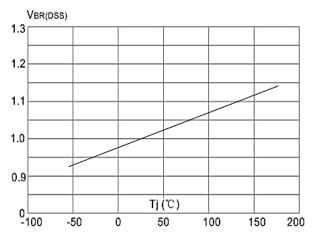


Figure 7: Normalized Breakdown Voltage vs Junction Temperature

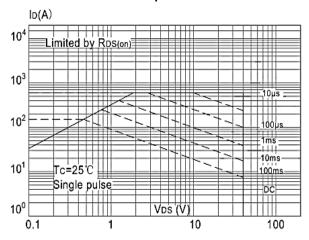


Figure 9: Maximum Safe Operating Area

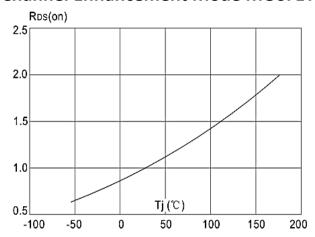


Figure 8: Normalized on Resistance vs.

Junction Temperature

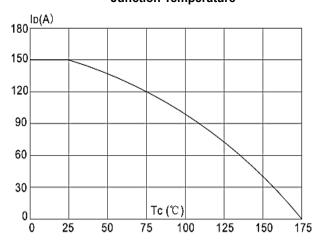


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

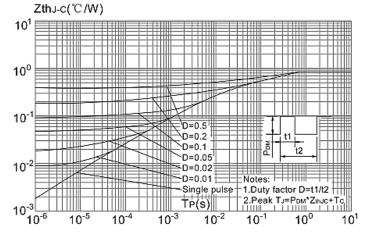
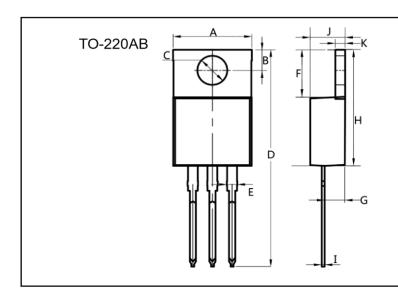
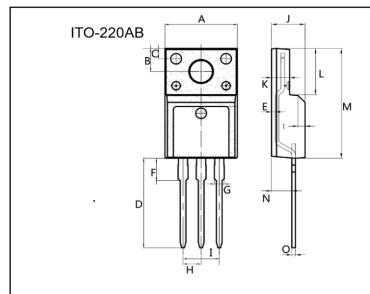


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambien

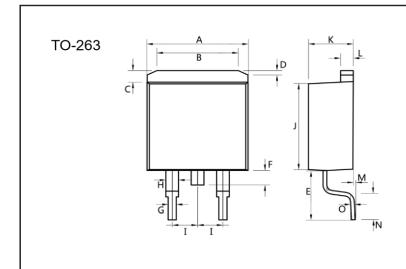




| Dim.                         | Min. | Max. |
|------------------------------|------|------|
| Α                            | 10.0 | 10.4 |
| В                            | 2.5  | 3.0  |
| С                            | 3.5  | 4.0  |
| D                            | 28.0 | 30.0 |
| Е                            | 1.1  | 1.5  |
| F                            | 6.2  | 6.6  |
| G                            | 2.9  | 3.3  |
| Н                            | 15.0 | 16.0 |
| I                            | 0.35 | 0.45 |
| J                            | 4.3  | 4.7  |
| K                            | 1.2  | 1.4  |
| All Dimensions in millimeter |      |      |



| Min.                         | Max.  |  |
|------------------------------|---|--|
| 9.9                          | 10.3  |  |
| 2.9                          | 3.5   |  |
| 1.15                         | 1.45  |  |
| 12.75                        | 13.25   |  |
| 0.55                         | 0.75  |  |
| 3.1                          | 3.5   |  |
| 1.25                         | 1.45  |  |
| Typ 2.54                     |   |  |
| Typ 5.08                     |   |  |
| 4.55                         | 4.75  |  |
| 2.4                          | 2. 7  |  |
| 6.35                         | 6.75  |  |
| 15.0                         | 16.0  |  |
| 2.75                         | 3.15  |  |
| 0.45                         | 0.60  |  |
| All Dimensions in millimeter |   |  |
|                              | 9.9 2.9 1.15 12.75 0.55 3.1 1.25 Typ Typ 4.55 2.4 6.35 15.0 2.75 0.45 |  |



| Dim.                         | Min.         | Max.     |  |
|------------------------------|--------------|----------|--|
| Α                            | 10.0         | 10. 5    |  |
| В                            | 7.25         | 7.75     |  |
| С                            | 1.3          | 1.5      |  |
| D                            | 0.55         | 0.75     |  |
| E                            | 5.0          | 6.0      |  |
| F                            | 1.4          | 1.6      |  |
| G                            | 0.75         | 0.95     |  |
| Н                            | 1.15         | 1.35     |  |
| ı                            | Typ 2.54     |          |  |
| J                            | 8.4          | 8.6      |  |
| K                            | 4.4          | 4.6      |  |
| L                            | 1.25         | 1.45     |  |
| М                            | 0.02         | 0.1      |  |
| N                            | 2.4          | 2.8      |  |
| О                            | 0.35         | 0.45     |  |
| All Dimensions in millimeter |              |          |  |
| All Dim                      | ensions in m | llimeter |  |





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# AP120N04P/T

# **40V N-Channel Enhancement Mode MOSFET**

| Edition | Date     | Change          |
|---------|----------|-----------------|
| Rve1.0  | 2020/4/1 | Initial release |

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DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
IPB80P04P405ATMA2 2N7002W-G MCAC30N06Y-TP MCQ7328-TP BXP7N65D BXP4N65F AOL1454G WMJ80N60C4 BXP2N20L
BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13 SLF10N65ABV2
BSO203SP BSO211P IPA60R230P6 IPA60R460CE